

Title (en)

AUTOMATED DIRECT EMULSION PROCESS FOR MAKING PRINTED CIRCUITS AND MULTILAYER PRINTED CIRCUITS

Title (de)

AUTOMATISIERTER DIREKTEMULSIONSPROZESS ZUR HERSTELLUNG VON LEITERPLATTEN UND MEHRSCICHTIGEN LEITERPLATTEN

Title (fr)

PROCÉDÉ D'ÉMULSION PHOTOSENSIBLE AUTOMATISÉE POUR LA FABRICATION DE CIRCUITS IMPRIMÉS ET DE CIRCUITS IMPRIMÉS MULTICOUCHES

Publication

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Application

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Priority

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- US 94473107 P 20070618

Abstract (en)

[origin: WO2008157642A1] A method for making multilayer printed circuits includes a) coating a non-metallized substrate with a solution which creates a light sensitive surface on the substrate, b) imaging the coated substrate with a circuit design, c) developing the imaged substrate, d) directly plating the developed image onto the coated substrate, e) coating the plated substrate with a liquid photoimageable cover coat, f) imaging the coated plated substrate with a predesigned circuitry, g) developing the liquid photoimageable cover coat, and repeating steps a) through d). Steps e) through g) are then repeated followed by steps a) through d) until a desired number of layers is achieved for the multilayer circuit. The method may be automated by having a conveyer like system which automatically unrolls and directs a roll of non-metallized substrate through various coating, imaging, developing, and plating stations.

IPC 8 full level

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